



Click [here](#) for the 3D model.

| Dimensions | |
|------------|------------------|
| Chip Size | 0603 |
| L | 1.6mm +/-0.17mm |
| W | 0.8mm +/-0.15mm |
| T | 0.8mm +/-0.15mm |
| S | 0.58mm MIN |
| B | 0.45mm +/-0.15mm |

| Packaging Specifications | |
|--------------------------|------------------------|
| Packaging | T&R, 330mm, Paper Tape |
| Packaging Quantity | 15000 |

| General Information | |
|---------------------|---------------------------------|
| Series | SMD Comm COG Flex |
| Style | SMD Chip |
| Description | SMD, MLCC, FT-CAP, Ultra-Stable |
| Features | FT-CAP, Ultra-Stable |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 4.6 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|------------------------|
| Capacitance | 33 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Capacitance Tolerance | 5% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

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